ABSTRACT

Provided is a wafer-holding ring member (10) used for a polishing apparatus, the wafer-holding ring member including a polishing surface (12), in which the wafer-holding ring member is made of a silicon material. It is preferable that the wafer-holding ring member is made of a silicon material having a purity of 99.9999 mass% or more. It is preferable that a contact angle of water on the polishing surface (12) is 30° or less.